

SN55110A, SN75110A, SN75112 DUAL LINE DRIVERS

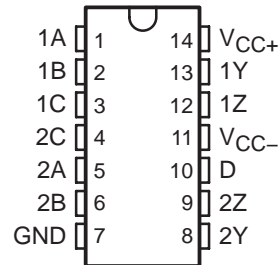
SLLS106G – DECEMBER 1975 – REVISED NOVEMBER 2004

- Improved Stability Over Supply Voltage and Temperature Ranges
- Constant-Current Outputs
- High Speed
- Standard Supply Voltages
- High Output Impedance
- High Common-Mode Output Voltage Range
... -3 V to 10 V
- TTL-Input Compatibility
- Inhibitor Available for Driver Selection
- Glitch Free During Power Up/Power Down
- SN75112 and External Circuit Meets or Exceeds the Requirements of CCITT Recommendation V.35

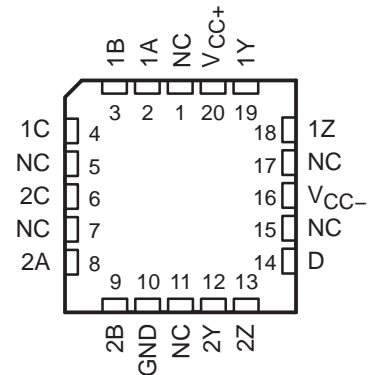
description/ordering information

The SN55110A, SN75110A, and SN75112 dual line drivers have improved output current regulation with supply-voltage and temperature variations. In addition, the higher current of the SN75112 (27 mA) allows data to be transmitted over longer lines. These drivers offer optimum performance when used with the SN55107A, SN75107A, and SN75108A line receivers.

SN55110A ... J OR W PACKAGE
SN75110A ... D, N, OR NS PACKAGE
SN75112 ... D OR N PACKAGE
(TOP VIEW)



SN55110A ... FK PACKAGE
(TOP VIEW)



NC – No internal connection

ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP (N)	Tube of 25	SN75110AN	SN75110AN
		Tube of 50	SN75112N	SN75112N
	SOIC (D)	Reel of 2500	SN75110AD	SN75110A
		Tube of 50	SN75112D	
		Reel of 2500	SN75112DR	SN75112
		Tube of 50	SN75110ADR	
SOP (NS)	Reel of 2000	SN75110ANSR	SN75110A	
-55°C to 125°C	CDIP (J)	Tube of 25	SN55110AJ	SN55110AJ
		Tube of 150	SNJ55110AJ	SNJ55110AJ
	CFP (W)	Tube of 150	SNJ55110AW	SNJ55110AW
	LCCC (FK)	Tube of 55	SNJ55110AFK	SNJ55110AFK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2004, Texas Instruments Incorporated
On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SN55110A, SN75110A, SN75112 DUAL LINE DRIVERS

SLLS106G – DECEMBER 1975 – REVISED NOVEMBER 2004

description/ordering information (continued)

These drivers feature independent channels with common voltage supply and ground terminals. The significant difference between the three drivers is in the output-current specification. The driver circuits feature a constant output current that is switched to either of two output terminals by the appropriate logic levels at the input terminals. The output current can be switched off (inhibited) by low logic levels on the enable inputs. The output current nominally is 12 mA for the '110A devices and is 27 mA for the SN75112.

The enable/inhibit feature is provided so the circuits can be used in party-line or data-bus applications. A strobe or inhibitor (enable D), common to both drivers, is included for increased driver-logic versatility. The output current in the inhibited mode, $I_{O(off)}$, is specified so that minimum line loading is induced when the driver is used in a party-line system with other drivers. The output impedance of the driver in the inhibited mode is very high. The output impedance of a transistor is biased to cutoff.

The driver outputs have a common-mode voltage range of -3 V to 10 V , allowing common-mode voltage on the line without affecting driver performance.

All inputs are diode clamped and are designed to satisfy TTL-system requirements. The inputs are tested at 2 V for high-logic-level input conditions and 0.8 V for low-logic-level input conditions. These tests ensure 400-mV noise margin when interfaced with TTL Series 54/74 devices.

The SN55110A is characterized for operation over the full military temperature range of -55°C to 125°C . The SN75110A and SN75112 are characterized for operation from 0°C to 70°C .

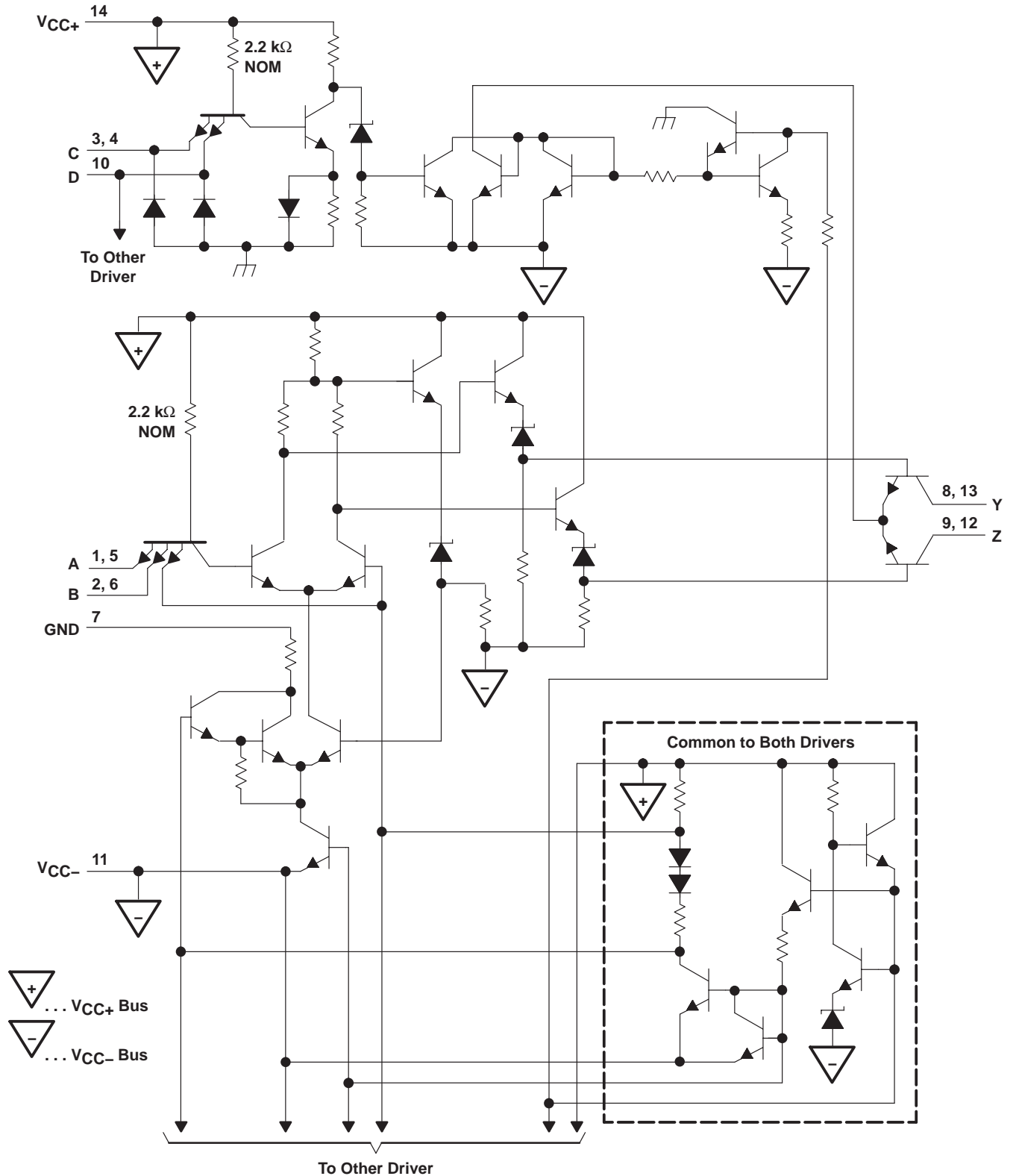
FUNCTION TABLE
(each driver)

LOGIC INPUTS		ENABLE INPUTS		OUTPUTS†	
A	B	C	D	Y	Z
X	X	L	X	Off	Off
X	X	X	L	Off	Off
L	X	H	H	On	Off
X	L	H	H	On	Off
H	H	H	H	Off	On

H = high level, L = low level, X = irrelevant

† When using only one channel of the line drivers, the other channel should be inhibited and/or have its outputs grounded.

schematic (each driver)



Pin numbers shown are for the D, J, N, NS, and W packages.

SN55110A, SN75110A, SN75112 DUAL LINE DRIVERS

SLLS106G – DECEMBER 1975 – REVISED NOVEMBER 2004

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage: V_{CC+} (see Note 1)	7 V
V_{CC-} (see Note 1)	-7 V
Input voltage, V_I	5.5 V
Output voltage range, V_O	-5 V to 12 V
Package thermal impedance, θ_{JA} (see Notes 2 and 3): D package	86°C/W
N package	80°C/W
NS package	76°C/W
Package thermal impedance, θ_{JC} (see Notes 4 and 5): FK package	13.42°C/W
J package	15.05°C/W
W package	14.65°C/W
Operating virtual junction temperature	150°C
Case temperature for 60 seconds: FK package	260°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: J or W package	300°C
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. Voltage values are with respect to network ground terminal.
 2. Maximum power dissipation is a function of $T_J(\text{max})$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 3. The package thermal impedance is calculated in accordance with JESD 51-7.
 4. Maximum power dissipation is a function of $T_J(\text{max})$, θ_{JC} , and T_C . The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_J(\text{max}) - T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 5. The package thermal impedance is calculated in accordance with MIL-STD-883.

recommended operating conditions (see Note 6)

	SN55110A			SN75110A SN75112			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC+} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{CC-} Supply voltage	-4.5	-5	-5.5	-4.75	-5	-5.25	V
Positive common-mode output voltage	0		10	0		10	V
Negative common-mode output voltage	0		-3	0		-3	V
V_{IH} High-level input voltage	2			2			V
V_{IL} Low-level output voltage			0.8			0.8	V
T_A Operating free-air temperature	-55		125	0		70	°C

NOTE 6: When using only one channel of the line drivers, the other channel should be inhibited and/or have its outputs grounded.



SN55110A, SN75110A, SN75112 DUAL LINE DRIVERS

SLLS106G – DECEMBER 1975 – REVISED NOVEMBER 2004

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†	SN55110A SN75110A			SN75112			UNIT
			MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	Input clamp voltage	$V_{CC\pm} = \text{MIN}$, $I_L = -12 \text{ mA}$	-0.9	-1.5		-0.9	-1.5	V	
$I_{O(\text{on})}$	On-state output current	$V_{CC\pm} = \text{MAX}$, $V_O = 10 \text{ V}$	12	15		27	40	mA	
		$V_{CC} = \text{MIN to MAX}$, $V_O = -1 \text{ V to } 1 \text{ V}$, $T_A = 25^\circ\text{C}$				24	28		32
		$V_{CC\pm} = \text{MIN}$, $V_O = -3 \text{ V}$	6.5	12		15	27		
$I_{O(\text{off})}$	Off-state output current	$V_{CC\pm} = \text{MIN}$, $V_O = 10 \text{ V}$			100			100	μA
I_I	Input current at maximum input voltage	A, B, or C inputs	$V_{CC\pm} = \text{MAX}$, $V_I = 5.5 \text{ V}$			1			1
		D input							
I_{IH}	High-level input current	A, B, or C inputs	$V_{CC\pm} = \text{MAX}$, $V_I = 2.4 \text{ V}$			40			40
		D input							
I_{IL}	Low-level input current	A, B, or C inputs	$V_{CC\pm} = \text{MAX}$, $V_I = 0.4 \text{ V}$			-3			-3
		D input							
$I_{CC+(\text{on})}$	Supply current from V_{CC} with driver enabled	$V_{CC\pm} = \text{MAX}$, A and B inputs at 0.4 V, C and D inputs at 2 V	23	35		25	40	mA	
$I_{CC-(\text{on})}$	Supply current from V_{CC-} with driver enabled	$V_{CC\pm} = \text{MAX}$, A and B inputs at 0.4 V, C and D inputs at 2 V	-34	-50		-65	-100	mA	
$I_{CC+(\text{off})}$	Supply current from V_{CC-} with driver inhibited	$V_{CC\pm} = \text{MAX}$, A, B, C, and D inputs at 0.4 V	21			30		mA	
$I_{CC-(\text{off})}$	Supply current from $V_{CC\pm}$ with driver inhibited	$V_{CC\pm} = \text{MAX}$, A, B, C, and D inputs at 0.4 V	-17			-32		mA	

† For conditions shown as MIN or MAX, use appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC+} = 5 \text{ V}$, $V_{CC-} = -5 \text{ V}$, $T_A = 25^\circ\text{C}$.

switching characteristics, $V_{CC\pm} = \pm 5 \text{ V}$, $T_A = 25^\circ\text{C}$ (see Figure 1)

PARAMETERS§	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	A or B	Y or Z	$C_L = 40 \text{ pF}$, $R_L = 50 \Omega$,		9		15	ns
t_{PHL}					9		15	
t_{PLH}	C or D	Y or Z	$C_L = 40 \text{ pF}$, $R_L = 50 \Omega$,		16		25	ns
t_{PHL}					13		25	

§ t_{PLH} = propagation delay time, low- to high-level output

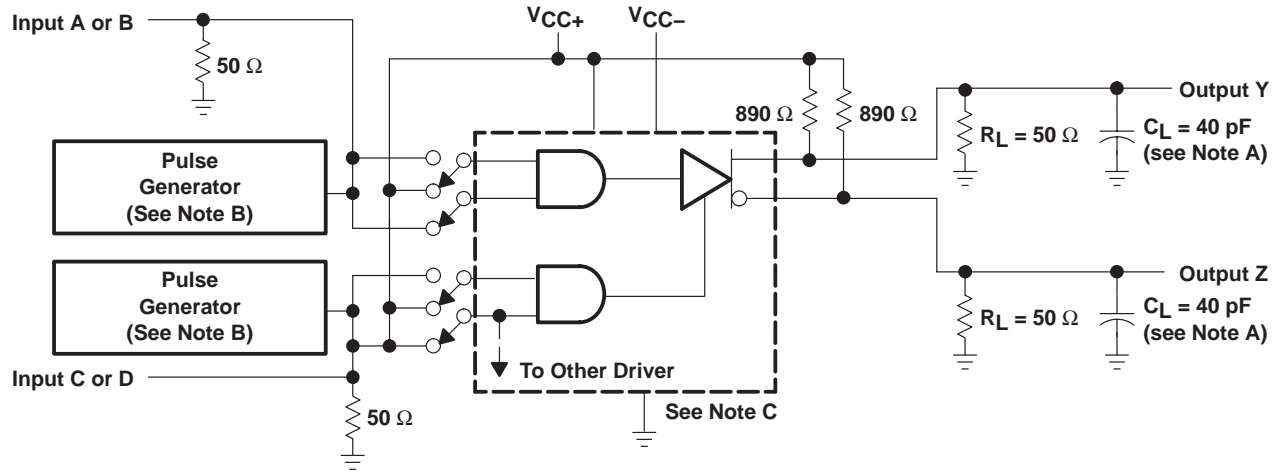
t_{PHL} = propagation delay time, high- to low-level output



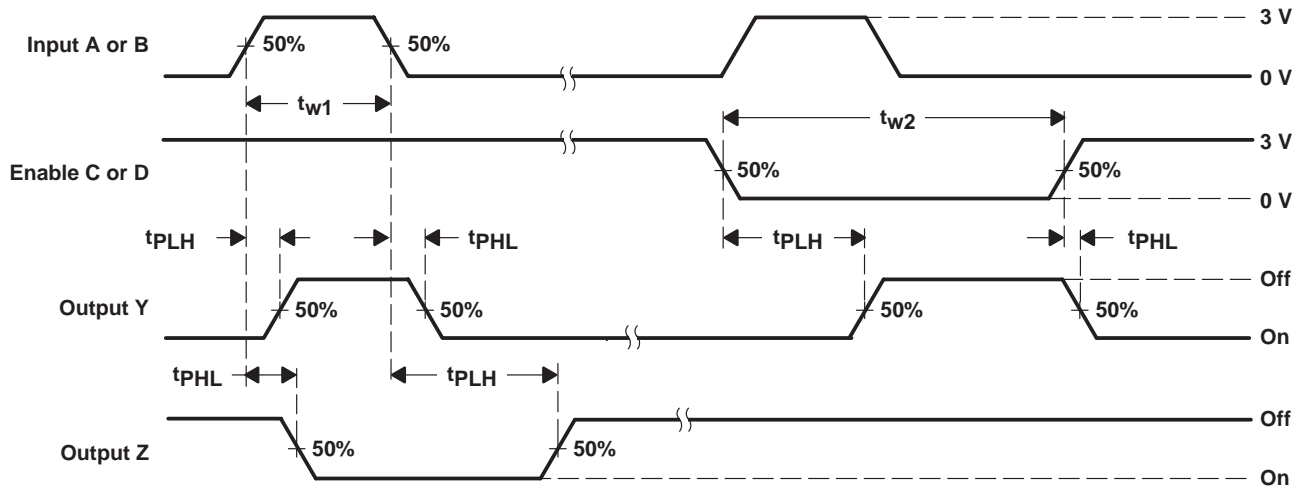
SN55110A, SN75110A, SN75112 DUAL LINE DRIVERS

SLLS106G – DECEMBER 1975 – REVISED NOVEMBER 2004

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT



VOLTAGE WAVEFORMS

- NOTES: A. C_L includes probe and jig capacitance.
 B. The pulse generators have the following characteristics: $Z_O = 50 \Omega$, $t_r = t_f = 10 \pm 5 \text{ ns}$, $t_{w1} = 500 \text{ ns}$, $\text{PRR} \leq 1 \text{ MHz}$, $t_{w2} = 1 \mu\text{s}$, $\text{PRR} \leq 500 \text{ kHz}$.
 C. For simplicity, only one channel and the enable connections are shown.

Figure 1. Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

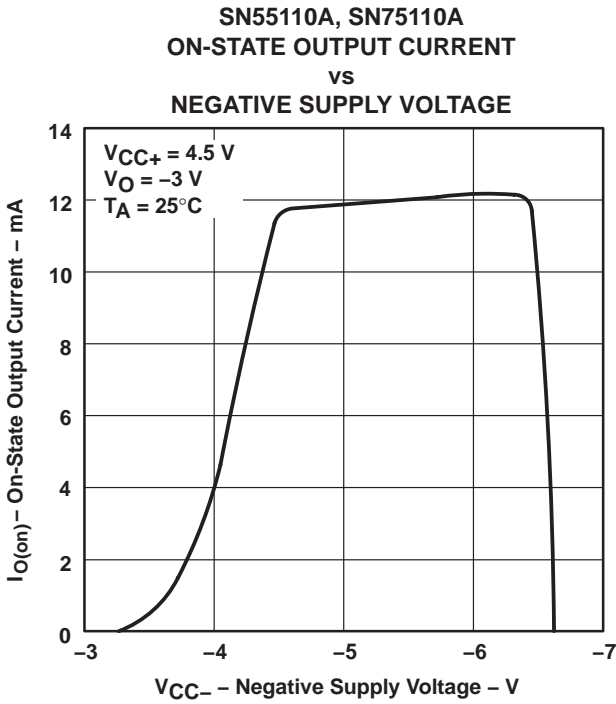


Figure 2

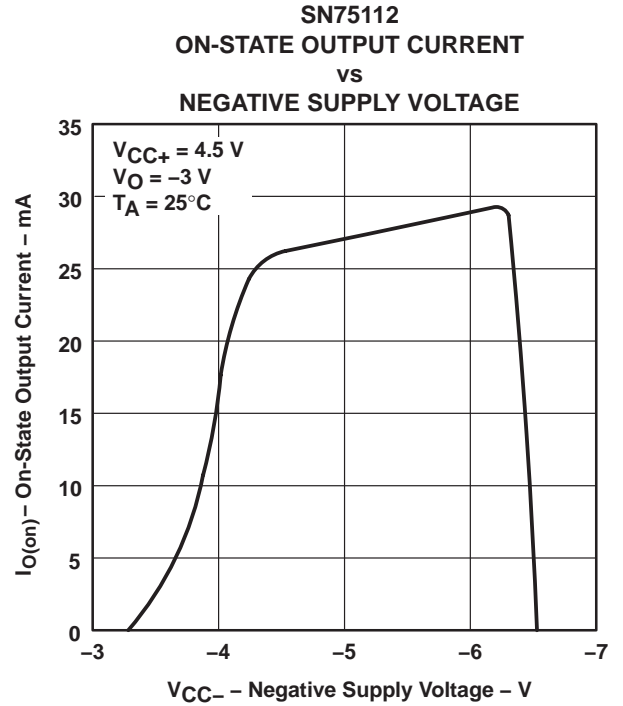


Figure 3

SN55110A, SN75110A, SN75112 DUAL LINE DRIVERS

SLLS106G – DECEMBER 1975 – REVISED NOVEMBER 2004

APPLICATION INFORMATION

special pulse-control circuit

Figure 4 shows a circuit that can be used as a pulse-generator output or in many other testing applications.

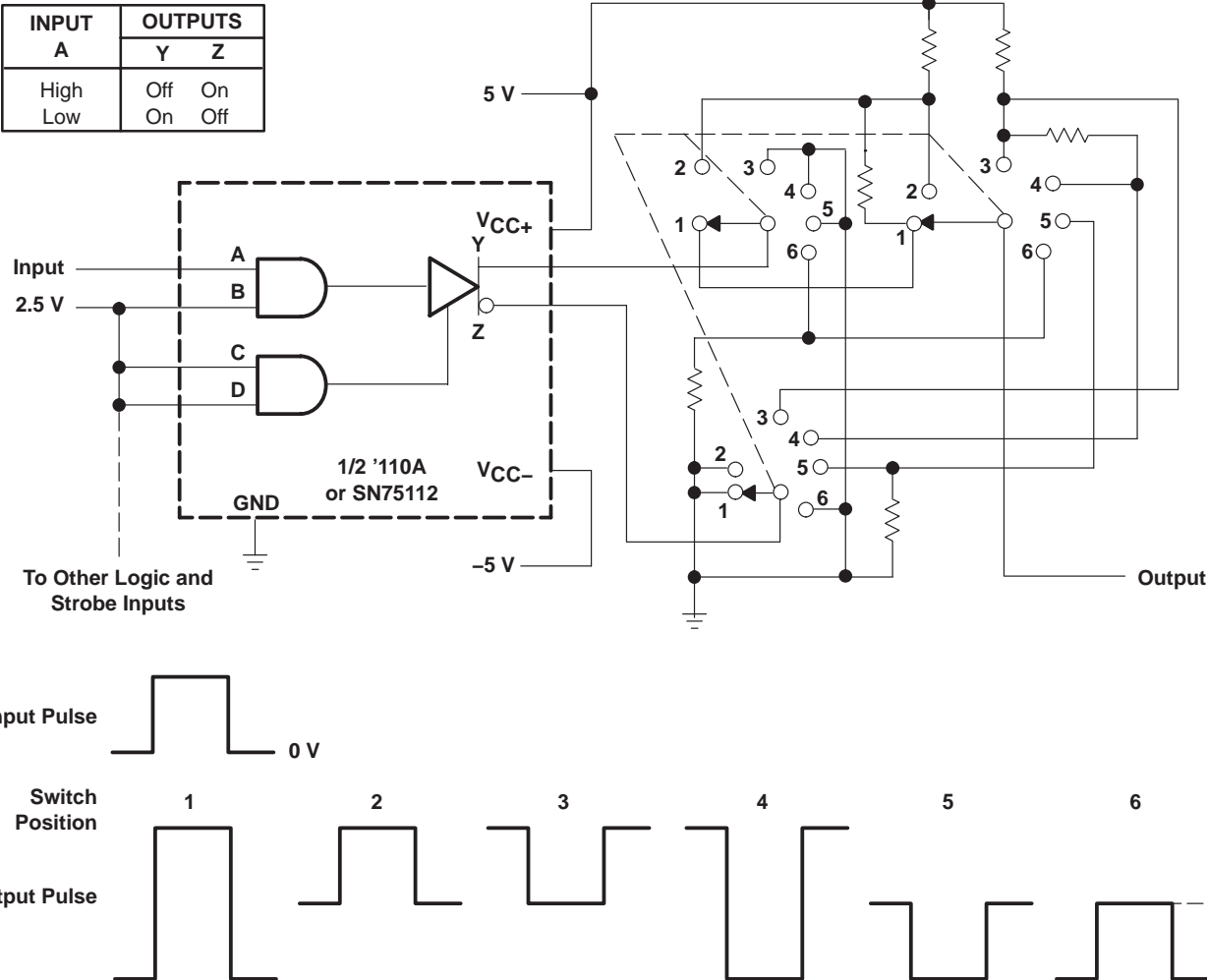


Figure 4. Pulse-Control Circuit

APPLICATION INFORMATION

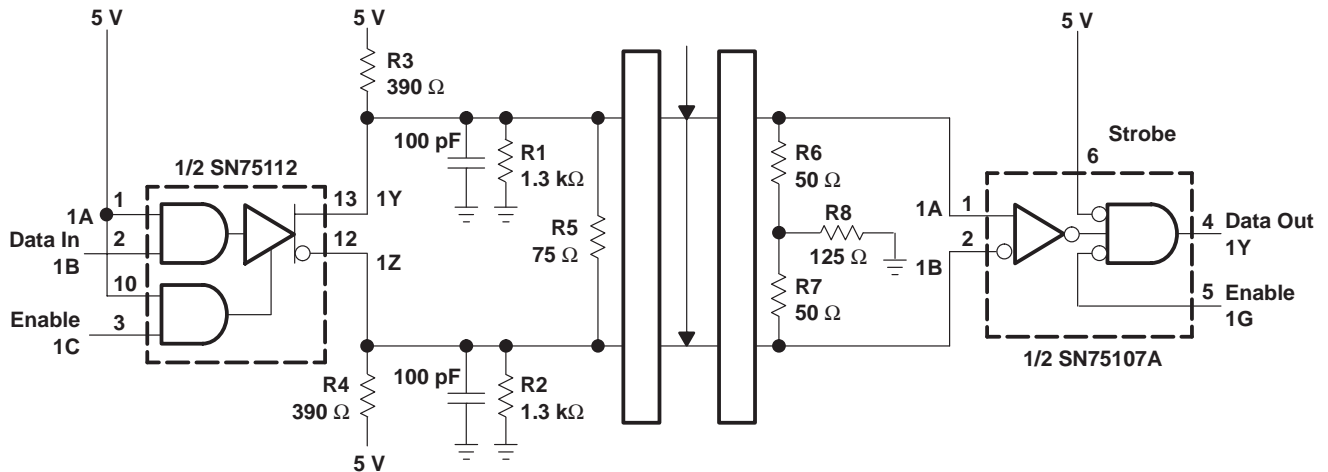
using the SN75112 as a CCITT-recommended V.35 line driver

The SN75112 dual line driver, the SN75107A dual line receiver, and some external resistors can be used to implement the data-interchange circuit of CCITT recommendation V.35 (1976) modem specification. The circuit of one channel is shown in Figure 5 and meets the requirement of the interface as specified by Appendix 11 of CCITT V.35 and is summarized in Table 1 (V.35 has been replaced by ITU V.11).

Table 1. CCITT V.35 Electrical Requirements

GENERATOR	MIN	MAX	UNIT
Source impedance, Z_{source}	50	150	Ω
Resistance to ground, R	135	165	Ω
Differential output voltage, V_{OD}	440	660	mV
10% to 90% rise time, t_r	40		ns
or	0.01 \times ui^\dagger		
Common-mode output voltage, V_{OC}	-0.6	0.6	V
LOAD (RECEIVER)	MIN	MAX	UNIT
Input impedance, Z_I	90	110	Ω
Resistance to ground, R	135	165	Ω

\dagger ui = unit interval or minimum signal-element pulse duration



All resistors are 5%, 1/4 W.

Figure 5. CCITT-Recommended V.35 Interface Using the SN75112 and SN75107A

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-87547012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-8754701CA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Call TI	
5962-8754701DA	ACTIVE	CFP	W	14	1	TBD	Call TI	Call TI	
SN55110AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN75110AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75110ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75110ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75110ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75110ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75110ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75110AJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SN75110AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN75110ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN75110ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75110ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75110ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75112D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75112DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75112DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75112DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN75112DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75112DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75112N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN75112NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SNJ55110AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ55110AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ55110AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN55110A, SN75110A :

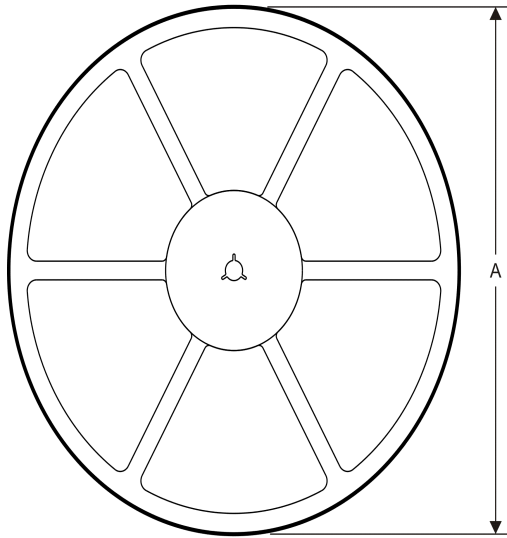
- Catalog: [SN75110A](#)
- Military: [SN55110A](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75110ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN75110ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN75110ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN75112DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75110ADR	SOIC	D	14	2500	333.2	345.9	28.6
SN75110ADR	SOIC	D	14	2500	367.0	367.0	38.0
SN75110ANSR	SO	NS	14	2000	367.0	367.0	38.0
SN75112DR	SOIC	D	14	2500	367.0	367.0	38.0

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

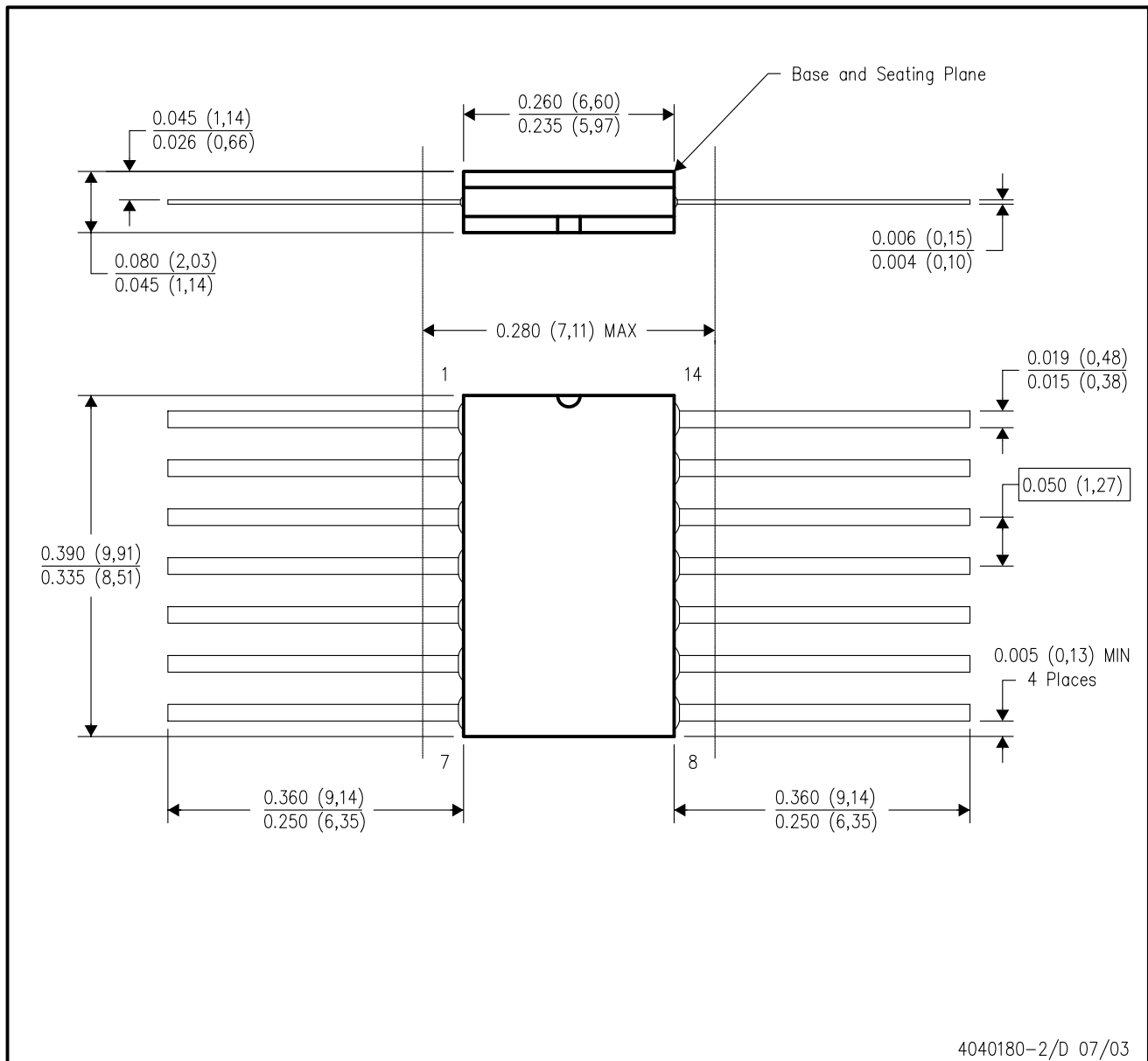


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

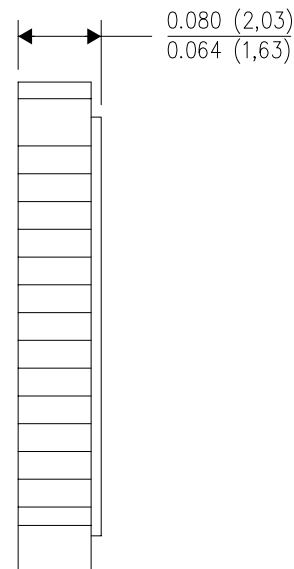
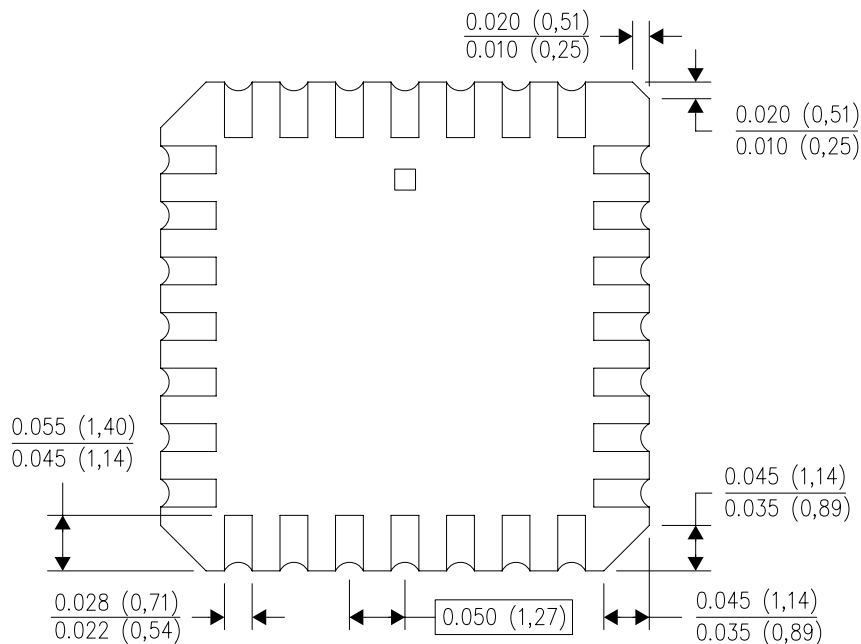
FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE

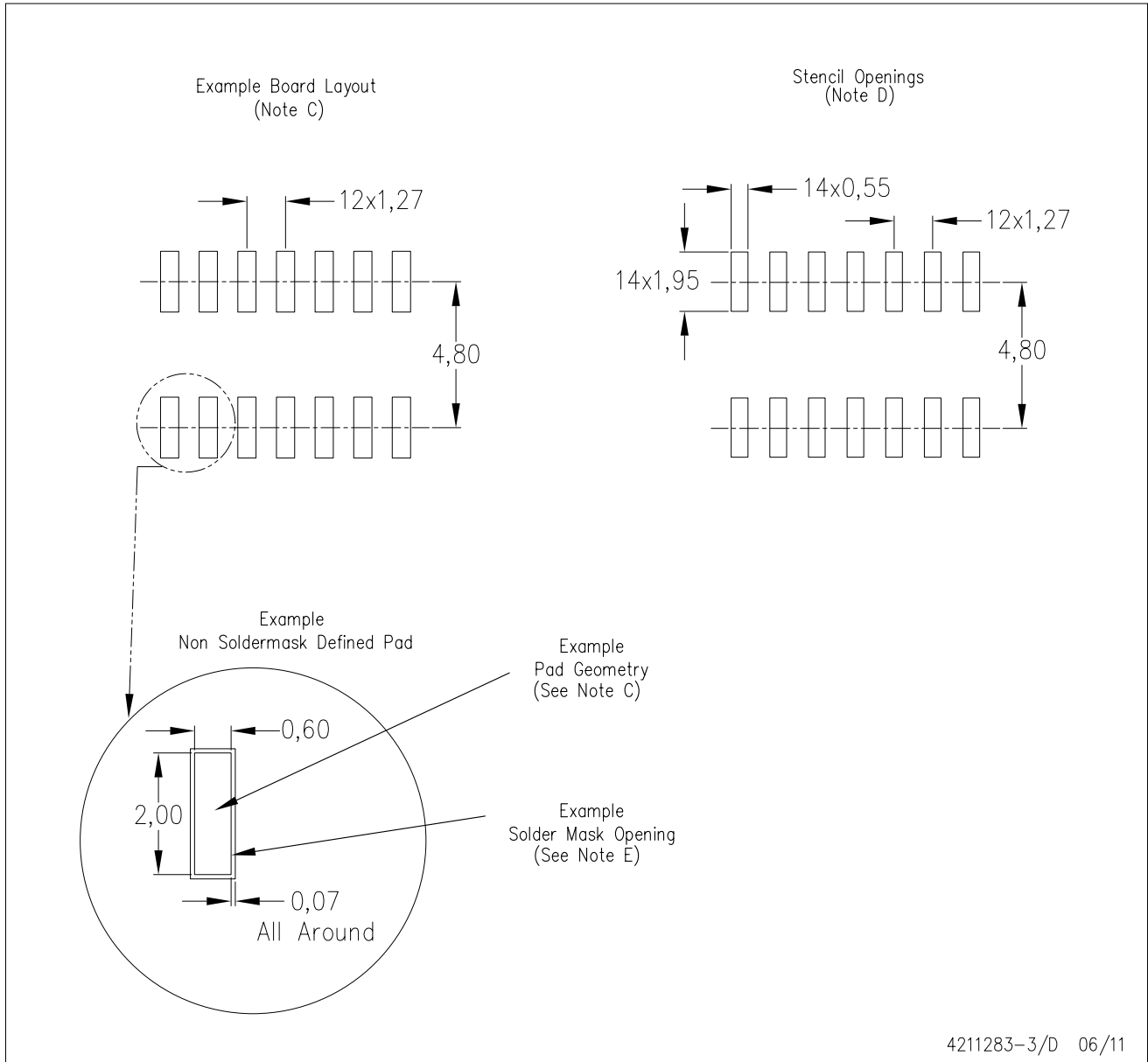


4040047-5/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46C and to discontinue any product or service per JESD48B. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Mobile Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community e2e.ti.com